#### **Features**

- · Fast Read Access Time 45 ns
- Low-Power CMOS Operation
  - 100 μA max. Standby
  - 20 mA max. Active at 5 MHz
- JEDEC Standard Packages
  - 28-Lead 600-mil PDIP
  - 32-Lead PLCC
  - 28-Lead TSOP and SOIC
- 5V ± 10% Supply
- · High-Reliability CMOS Technology
  - 2,000V ESD Protection
  - 200 mA Latchup Immunity
- Rapid<sup>™</sup> Programming Algorithm 100 µs/byte (typical)
- CMOS and TTL Compatible Inputs and Outputs
- Integrated Product Identification Code
- · Commercial, Industrial and Automotive Temperature Ranges

#### Description

The AT27C512R is a low-power, high-performance 524,288-bit one-time programmable read only memory (OTP EPROM) organized 64K by 8 bits. It requires only one 5V power supply in normal read mode operation. Any byte can be accessed in less than 45 ns, eliminating the need for speed reducing WAIT states on high-performance microprocessor systems.

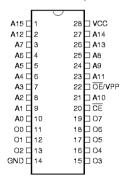
Atmel's scaled CMOS technology provides high-speed, lower active power consumption, and significantly faster programming. Power consumption is typically only 8 mA in Active Mode and less than 10  $\mu$ A in Standby.

(continued)

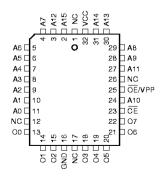
#### **Pin Configurations**

Pin Name	Function
A0 to A15	Addresses
00 - 07	Outputs
CE	Chip Enable
ŌE/VPP	Output Enable/VPP
NC	No Connect

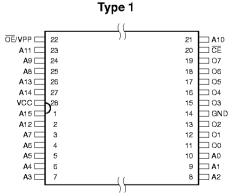
PDIP, SOIC Top View



PLCC Top View



TSOP Top View



Note: PLCC Package Pins 1 and 17 are DON'T CONNECT.





512K (64K x 8) OTP EPROM

AT27C512R

Rev. 0015I-07/98



The AT27C512R is available in a choice of industry standard JEDEC-approved one-time programmable (OTP) plastic PDIP, PLCC, SOIC, and TSOP packages. All devices feature two-line control ( $\overline{CE}$ ,  $\overline{OE}$ ) to give designers the flexibility to prevent bus contention.

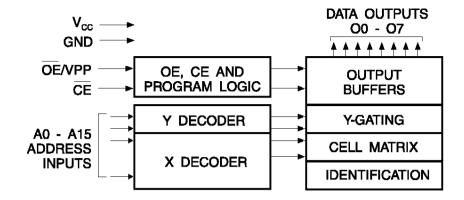
With 64K byte storage capability, the AT27C512R allows firmware to be stored reliably and to be accessed by the system without the delays of mass storage media.

Atmel's 27C512R has additional features to ensure high quality and efficient production use. The Rapid™ Programming Algorithm reduces the time required to program the part and guarantees reliable programming. Programming time is typically only 100 µs/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry standard programming equipment to select the proper programming algorithms and voltages.

#### **System Considerations**

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed data sheet limits, resulting in device non-conformance. At a minimum, a 0.1  $\mu F$  high frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the  $V_{\rm CC}$  and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a 4.7  $\mu F$  bulk electrolytic capacitor should be utilized, again connected between the  $V_{\rm CC}$  and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

#### **Block Diagram**



#### **Absolute Maximum Ratings\***

Temperature Under Bias55°C to + 125°C	3
Storage Temperature65°C to + 150°C	2
Voltage on Any Pin with Respect to Ground2.0V to + 7.0V <sup>(1)</sup>	
Voltage on A9 with Respect to Ground2.0V to + 14.0V <sup>(1)</sup>	
V <sub>PP</sub> Supply Voltage with Respect to Ground2.0V to + 14.0V <sup>(1)</sup>	

\*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note:

1. Minimum voltage is -0.6V dc which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is V<sub>CC</sub> + 0.75V dc which may overshoot to +7.0 volts for pulses of less than 20 ns.

## **Operating Modes**

Mode\Pin	CE	OE/V <sub>PP</sub>	Ai	Outputs
Read	V <sub>IL</sub>	V <sub>IL</sub>	Ai	D <sub>OUT</sub>
Output Disable	V <sub>IL</sub>	V <sub>IH</sub>	X <sup>(1)</sup>	High Z
Standby	V <sub>IH</sub>	X <sup>(1)</sup>	Х	High Z
Rapid Program <sup>(2)</sup>	V <sub>IL</sub>	$V_{PP}$	Ai	D <sub>IN</sub>
PGM Inhibit	V <sub>IH</sub>	$V_{PP}$	X <sup>(1)</sup>	High Z
Product Identification <sup>(4)</sup>	V <sub>IL</sub>	V <sub>IL</sub>	A9 =V <sub>H</sub> <sup>(3)</sup> A0 = V <sub>IH</sub> or V <sub>IL</sub> A1 - A15 = V <sub>IL</sub>	Identification Code

- Notes: 1. X can be  $V_{IL}$  or  $V_{IH}$ .
  - 2. Refer to Programming Characteristics.
  - 3.  $V_H = 12.0 \pm 0.5 V$ .
  - Two identifier bytes may be selected. All Ai inputs are held low (V<sub>L</sub>), except A9 which is set to V<sub>H</sub> and A0 which is toggled low  $(V_{II})$  to select the Manufacturer's Identification byte and high  $(V_{IH})$  to select the Device Code byte.





### DC and AC Operating Conditions for Read Operation

				AT270	512R		
		-45	-55	-70	-90	-12	-15
	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°0	0°C - 70°
Operating Temp.(Case)	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°0	-40°C - 85°	C -40°C - 85
Tomp.(Oddo)	Auto.			-40°C - 125°C	-40°C - 125°C	-40°C - 125°C	-40°C - 125°C
V <sub>CC</sub> Supply		5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%

## DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition		Min	Max	Units
1	Innert Lood Correspond	V 0V+5 V	Com., Ind,		±1	μА
l <sub>LI</sub>	Input Load Current	$V_{IN} = 0V \text{ to } V_{CC}$	V <sub>IN</sub> = 0 V to V <sub>CC</sub> Auto.		±5	μА
1	Output Leakage	V 0V/4- V	Com., Ind,		±5	μА
l <sub>LO</sub>	Current	$V_{OUT} = 0V \text{ to } V_{CC}$	Auto.		±10	μА
1	V <sub>CC</sub> <sup>(1)</sup> Standby	$I_{SB1}$ (CMOS), $\overline{CE} = V_{CC\pm} 0.3V$			100	μА
I <sub>SB</sub>	Current	$I_{SB2}$ (TTL), $\overline{CE}$ = 2.0 to $V_{CC+}$ 0.5V			1	mA
Icc	V <sub>CC</sub> Active Current	$f = 5 \text{ MHz}, I_{OUT} = 0 \text{ mA}, \overline{CE} = V_{IL}$			20	mA
V <sub>IL</sub>	Input Low Voltage			-0.6	0.8	٧
V <sub>IH</sub>	Input High Voltage			2.0	V <sub>CC</sub> + 0.5	٧
V <sub>OL</sub>	Output Low Voltage	l <sub>OL</sub> = 2.1 mA			0.4	٧
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -400 μA		2.4		V

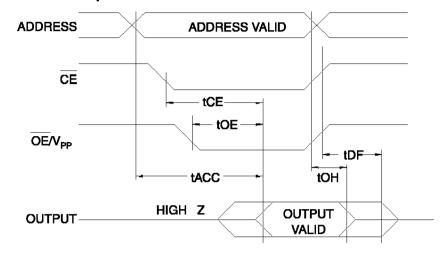
Notes: 1.  $V_{CC}$  must be applied simultaneously with or before  $\overline{OE}/V_{PP}$  and removed simultaneously with or after  $\overline{OE}/V_{PP}$ .

## **AC Characteristics for Read Operation**

			AT27C512R												
			-4	<b>4</b> 5	-{	55	-7	70	-6	90	-1	12	-1	15	
Symbol	Parameter	Condition	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Units
t <sub>ACC</sub> (3)	Address to Output Delay $\overline{CE} = \overline{OE}/V_{PP} = V_{IL}$			45		55		70		90		120		150	ns
t <sub>CE</sub> <sup>(2)</sup>	CE to Output Delay	$\overline{OE}/V_{PP} = V_{IL}$		45		55		70		90		120		150	ns
$t_{OE}^{(2)(3)}$	OE/V <sub>PP</sub> to Output Delay	CE = V <sub>IL</sub>		20		25		30		35		35		40	ns
t <sub>DF</sub> (4)(5)	OE/V <sub>PP</sub> or CE High to Output Float, whichever occurred first			20		20		25		25		30		35	ns
t <sub>OH</sub>	Output Hold from Address, CE or OE/V <sub>pp</sub> whichever occurred first		7		7		7		0		0		0		ns

Notes: 2, 3, 4, 5. - see AC Waveforms for Read Operation.

## AC Waveforms for Read Operation(1)

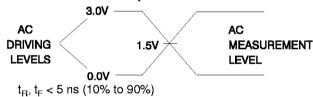


Notes: 1. Timing measurement reference level is 1.5V for -45 and -55 devices. Input AC drive levels are V<sub>IL</sub> = 0.0V and V<sub>IH</sub> = 3.0V. Timing measurement reference levels for all other speed grades are V<sub>OL</sub> = 0.8V and V<sub>OH</sub> = 2.0V. Input AC drive levels are V<sub>IL</sub> = 0.45V and V<sub>IH</sub> = 2.4V.

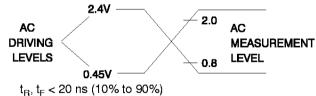
- 2.  $\overline{OE}/V_{PP}$  may be delayed up to  $t_{CE}$   $t_{OE}$  after the falling edge of  $\overline{CE}$  without impact on  $t_{CE}$ .
- 3.  $\overline{\text{OE}}/\text{V}_{PP}$  may be delayed up to  $t_{ACC}$   $t_{OE}$  after the address is valid without impact on  $t_{ACC}$ .
- 4. This parameter is only sampled and is not 100% tested.
- 5. Output float is defined as the point when data is no longer driven.

# Input Test Waveforms and Measurement Levels

For -45 and -55 devices only:

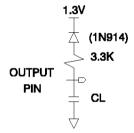


For -70, -90, -12, -15, and -20 devices:



th, th < 0 110 (10 10 to 00 10)

## **Output Test Load**



Note:  $C_L = 100 \text{ pF}$  including jig capacitance, except for the -45 and -55 devices, where  $C_L = 30 \text{ pF}$ .

## Pin Capacitance

 $(f = 1 MHz T = 25°C)^{(1)}$ 

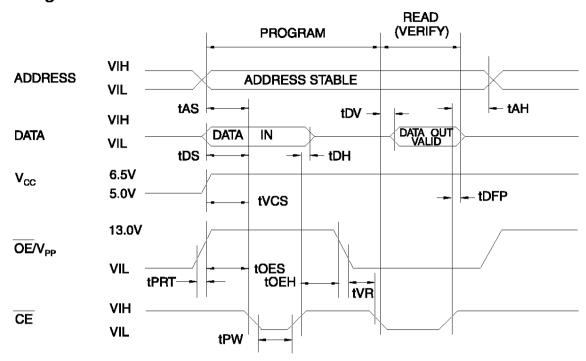
	Тур	Max	Units	Conditions
C <sub>IN</sub>	4	6	pF	V <sub>IN</sub> = 0V
C <sub>OUT</sub>	8	12	pF	V <sub>OUT</sub> = 0V

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.





## **Programming Waveforms**<sup>(1)</sup>



Notes: 1. The Input Timing Reference is 0.8V for  $V_{\rm IL}$  and 2.0V for  $V_{\rm IH}$ .

2.  $t_{OE}$  and  $t_{DFP}$  are characteristics of the device but must be accommodated by the programmer.

### **DC Programming Characteristics**

 $T_{A}$  = 25  $\pm$  5° C,  $V_{CC}$  = 6.5  $\pm$  0.25V,  $\overline{OE}/V_{PP}$  = 13.0  $\pm$  0.25V

			Limits		
Symbol	Parameter	Test Conditions	Min	Max	Units
l <sub>L1</sub>	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		±10	μА
V <sub>IL</sub>	Input Low Level		-0.6	0.8	V
V <sub>IH</sub>	Input High Level		2.0	V <sub>CC</sub> + 1	V
V <sub>OL</sub>	Output Low Voltage	l <sub>OL</sub> = 2.1 mA		0.4	V
V <sub>OH</sub>	Output High Voltage	l <sub>OH</sub> = -400 μA	2.4		V
I <sub>CC2</sub>	V <sub>CC</sub> Supply Current (Program and Verify)			25	mA
I <sub>PP2</sub>	ŌE/V <sub>PP</sub> Current	CE = V <sub>IL</sub>		25	mA
V <sub>ID</sub>	A9 Product Identification Voltage		11.5	12.5	V

## **AC Programming Characteristics**

 $T_A = 25 \pm 5$ °C,  $V_{CC} = 6.5 \pm 0.25$ V,  $\overline{OE}/V_{PP} = 13.0 \pm 0.25$ V

			Li	mits	
Symbol	Parameter	Test Conditions <sup>(1)</sup>	Min	Max	Units
t <sub>AS</sub>	Address Setup Time		2		μs
t <sub>OES</sub>	OE/V <sub>PP</sub> Setup Time		2		μs
t <sub>OEH</sub>	OE/V <sub>PP</sub> Hold Time	Input Rise and Fall Times	2		μs
t <sub>DS</sub>	Data Setup Time	(10% to 90%) 20ns	2		μs
t <sub>AH</sub>	Address Hold Time		0		μs
t <sub>DH</sub>	Data Hold Time	Input Pulse Levels 0.45V to 2.4V	2		μs
t <sub>DFP</sub>	CE High to Output Float Delay <sup>(2)</sup>	Input Timing Reference Level	0	130	ns
t <sub>vcs</sub>	V <sub>CC</sub> Setup Time	0.8V to 2.0V	2		μs
t <sub>PW</sub>	CE Program Pulse Width <sup>(3)</sup>		95	105	μs
t <sub>DV</sub>	Data Valid from $\overline{CE}^{(2)}$	Output Timing Reference Level 0.8V to 2.0V		1	μs
t <sub>vr</sub>	OE/V <sub>PP</sub> Recovery Time	3.37 10 2.37	2		μs
t <sub>PRT</sub>	OE/V <sub>PP</sub> Pulse Rise Time During Programming		50		ns

Notes: 1.  $V_{CC}$  must be applied simultaneously or before  $\overline{OE}/V_{PP}$  and removed simultaneously or after  $\overline{OE}/V_{PP}$ 

#### Atmel's 27C512R Integrated Product Identification Code

		Pins							Hex	
Codes	A0	07	<b>O</b> 6	<b>O</b> 5	04	О3	O2	01	00	Data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device Type	1	0	0	0	0	1	1	0	1	0D



<sup>2.</sup> This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven—see timing diagram.

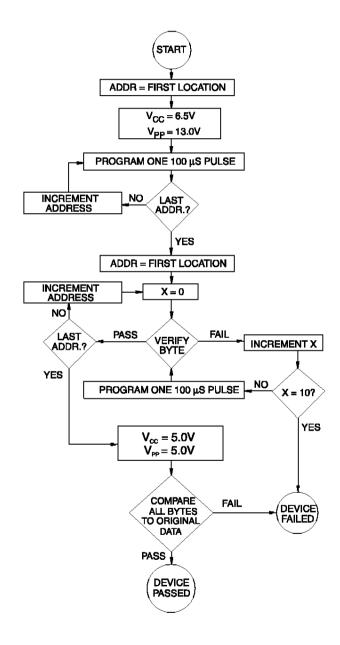
<sup>3.</sup> Program Pulse width tolerance is 100  $\mu$ sec  $\pm$  5%.



#### Rapid Programming Algorithm

A 100  $\mu s$   $\overline{CE}$  pulse width is used to program. The address is set to the first location.  $V_{CC}$  is raised to 6.5V and  $\overline{OE}/V_{PP}$  is raised to 13.0V. Each address is first programmed with one 100  $\mu s$   $\overline{CE}$  pulse without verification. Then a verification/reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100  $\mu s$  pulses are applied with a verification after each

pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked.  $\overline{\text{OE}}/\text{V}_{\text{PP}}$  is then lowered to  $\text{V}_{\text{IL}}$  and  $\text{V}_{\text{CC}}$  to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.



## **Ordering Information**

t <sub>ACC</sub>	I <sub>cc</sub>	(mA)					
(ns)	Active	Standby	Ordering Code	Package	Operation Range		
45	20	0.1	AT27C512R-45JC	32J	Commercial		
			AT27C512R-45PC	28P6	(0°C to 70°C)		
			AT27C512R-45RC	28R			
			AT27C512R-45TC	28T			
	20	0.1	AT27C512R-45JI	32J	Industrial		
			AT27C512R-45PI	28P6	(-40°C to 85°C)		
			AT27C512R-45RI	28R			
			AT27C512R-45TI	28T			
55	20	0.1	AT27C512R-55JC	32J	Commercial		
			AT27C512R-55PC	28P6	(0°C to 70°C)		
			AT27C512R-55RC	28R			
			AT27C512R-55TC	28T			
	20	0.1	AT27C512R-55JI	32J	Industrial		
			AT27C512R-55PI	28P6	(-40°C to 85°C)		
			AT27C512R-55RI	28R			
			AT27C512R-55TI	28T			
70	20	0.1	AT27C512R-70JC	32J	Commercial		
			AT27C512R-70PC	28P6	(0°C to 70°C)		
			AT27C512R-70RC	28R			
			AT27C512R-70TC	28T			
	20	0.1	AT27C512R-70JI	32J	Industrial		
			AT27C512R-70PI	28P6	(-40°C to 85°C)		
			AT27C512R-70RI	28R			
			AT27C512R-70TI	28T			
	20	0.1	AT27C512R-70JA	32J	Automotive		
			AT27C512R-70PA	28P6	(-40°C to 125°C)		
			AT27C512R-70RA	28R			

(continued)

	Package Type				
32J	2J 32-Lead, Plastic J-Leaded Chip Carrier (PLCC)				
28P6	28-Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)				
28R	28-Lead, 0.330" Wide, Plastic Gull Wing Small Outline (SOIC)				
28T	28-Lead, Thin Small Outline Package (TSOP)				





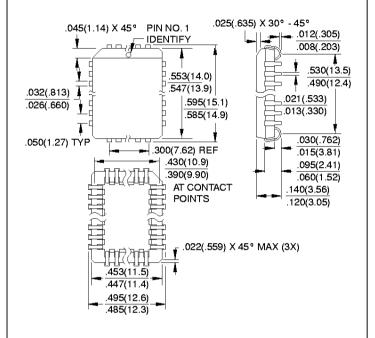
## Ordering Information (Continued)

t <sub>acc</sub> (ns)	I <sub>CC</sub> (mA)				
	Active	Standby	Ordering Code	Package	Operation Range
90	20	0.1	AT27C512R-90JC	<b>32</b> J	Commercial
			AT27C512R-90PC	28P6	(0°C to 70°C)
			AT27C512R-90RC	28R	
			AT27C512R-90TC	28T	
	20	0.1	AT27C512R-90JI	<b>32</b> J	Industrial
			AT27C512R-90PI	28P6	(-40°C to 85°C)
			AT27C512R-90RI	28R	
			AT27C512R-90TI	28T	
	20	0.1	AT27C512R-90JA	<b>32</b> J	Automotive
			AT27C512R-90PA	28P6	(-40°C to 125°C)
			AT27C512R-90RA	28R	
120	20	0.1	AT27C512R-12JC	<b>32</b> J	Commercial
			AT27C512R-12PC	28P6	(0°C to 70°C)
			AT27C512R-12RC	28R	
			AT27C512R-12TC	28T	
	20	0.1	AT27C512R-12JI	<b>32</b> J	Industrial
			AT27C512R-12PI	28P6	(-40°C to 85°C)
			AT27C512R-12RI	28R	
			AT27C512R-12TI	28T	
	20	0.1	AT27C512R-12JA	<b>32</b> J	Automotive
			AT27C512R-12PA	28P6	(-40°C to 125°C)
			AT27C512R-12RA	28R	
150	20	0.1	AT27C512R-15JC	<b>32</b> J	Commercial
			AT27C512R-15PC	28P6	(0°C to 70°C)
			AT27C512R-15RC	28R	
			AT27C512R-15TC	28T	
	20	0.1	AT27C512R-15JI	<b>32</b> J	Industrial
			AT27C512R-15PI	28P6	(-40°C to 85°C)
			AT27C512R-15RI	28R	
			AT27C512R-15TI	28T	
	20	0.1	AT27C512R-15JA	<b>32</b> J	Automotive
			AT27C512R-15PA	28P6	(-40°C to 125°C)
			AT27C512R-15RA	28R	

Package Type				
32J	32-Lead, Plastic J-Leaded Chip Carrier (PLCC)			
28P6	28-Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)			
28R	28-Lead, 0.330" Wide, Plastic Gull Wing Small Outline (SOIC)			
28T	28-Lead, Thin Small Outline Package (TSOP)			

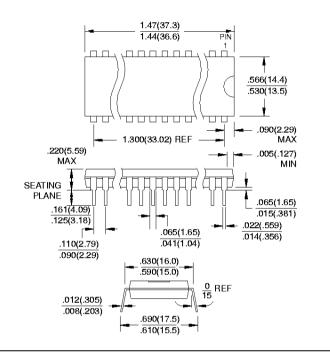
## **Packaging Information**

**32J**, 32-Lead, Plastic J-Leaded Chip Carrier (PLCC) Dimensions in Inches and (Millimeters) JEDEC STANDARD MS-016 AE



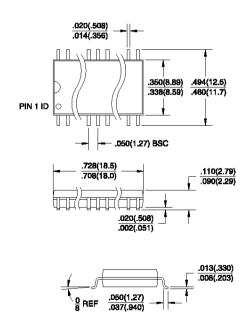
28P6, 28-Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)

Dimensions in Inches and (Millimeters)
JEDEC STANDARD MS-011 AB



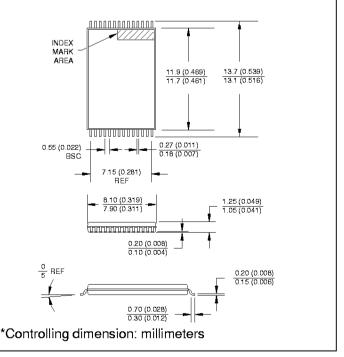
**28R**, 28-Lead, 0.330" Wide, Plastic Gull Wing Small Outline (SOIC)

Dimensions in Inches and (Millimeters)



**28T**, 28-Lead, Plastic Thin Small Outline Package (TSOP)

Dimensions in Millimeters and (Inches)\*







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